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Full Material Declaration for attached parts list

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Diotec Semiconductor

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 2 January 2014 [Approved on 19 December 2022, 09:15 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	11.5%	Gold	7440-57-5	8.5%
			ALUMINIUM	7429-90-5	12%
			Silicon	7440-21-3	79.5%
Die attach	Gold	3.5%	Tin	7440-31-5	20%
			Gold	7440-57-5	80%
Encapsulation	EP (Epoxy resin)	47.2%	Carbon black	1333-86-4	0.3%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	0.8%
			3,3',5,5'-Tetrabromobisphenol A Exempt from other regulatory requirements	79-94-7	0.99%
			Epoxy resin 89	26335-32-0	27.61%
			Quartz sand	60676-86-0	70.3%
Inner preparation	Gold	1.5%	Gold	7440-57-5	100%
Leadfinish	Tin plating	5.3%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	31%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-26/SOT-457	Diode/Transistor SMD	0.01	g